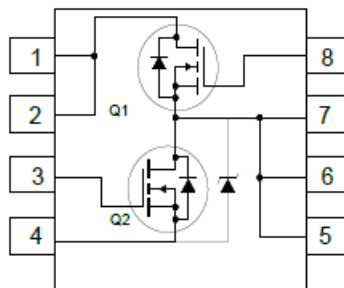
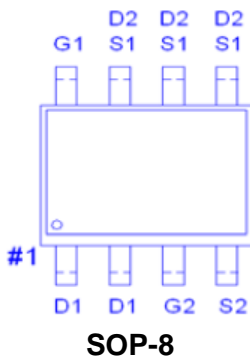


PD1303YVS

Dual N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D	Channel
30V	13m Ω @ $V_{GS} = 10V$	9A	Q1
30V	13m Ω @ $V_{GS} = 10V$	9A	Q2



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	CH.	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	Q1	30	V
			Q2	30	
Gate-Source Voltage		V_{GS}	Q1	± 20	
			Q2	± 20	
Continuous Drain Current ¹	$T_A = 25\text{ }^\circ\text{C}$	I_D	Q1	9	A
			Q2	9	
	$T_A = 70\text{ }^\circ\text{C}$		Q1	7.2	
			Q2	7.2	
Pulsed Drain Current ¹		I_{DM}	Q1	21	
			Q2	21	
Avalanche Current		I_{AS}	Q1	25	
			Q2	27	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	Q1	32	mJ
			Q2	36	
Power Dissipation	$T_A = 25\text{ }^\circ\text{C}$	P_D	Q1	1.7	W
			Q2		
	$T_A = 70\text{ }^\circ\text{C}$		Q1	1.1	
			Q2		
Junction & Storage Temperature Range		T_j, T_{stg}		-55 to 150	$^\circ\text{C}$

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THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL		TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	R _{θJA}	Q1		70	°C / W
	R _{θJA}	Q2		70	

¹Pulse width limited by maximum junction temperature.

²The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design.

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	CH.	LIMITS			UNITS
				MIN	TYP	MAX	
STATIC							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	Q1	30			V
			Q2	30			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	Q1	1	1.5	3	
			Q2	1	1.8	3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	Q1			±100	nA
			Q2			±100	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V	Q1			1	μA
			Q2			30	
		V _{DS} = 20V, V _{GS} = 0V, T _J = 55 °C	Q1			10	
			Q2			300	
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 4.5V, I _D = 7A	Q1		14	18.5	mΩ
			Q2		15	18.5	
		V _{GS} = 10V, I _D = 9A	Q1		10	13	
			Q2		10	13	
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 9A	Q1		28		S
			Q2		30		

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DYNAMIC									
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$	Q1	1040	pF				
			Q2	806					
Output Capacitance	C_{oss}		Q1	131					
			Q2	189					
Reverse Transfer Capacitance	C_{rss}		Q1	115					
			Q2	121					
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	Q1	1.5	Ω				
		Q2	2						
Total Gate Charge ²	Q_g	$V_{DS} = 15V, V_{GS} = 10V, I_D = 9V,$	Q1	23	nC				
Gate-Source Charge ²	Q_{gs}		Q2	18					
			Q1	3.5					
Gate-Drain Charge ²	Q_{gd}		Q2	4.1					
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 15V, I_D \cong 9A, V_{GS} = 10V, R_{GEN} = 6\Omega$	Q1	5.5	nS				
			Q2	4.7					
Rise Time ²	t_r		Q1	10					
			Q2	7.5					
Turn-Off Delay Time ²	$t_{d(off)}$		Q1	11					
			Q2	7.5					
Fall Time ²	t_f		Q1	32					
			Q2	27					
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)									
Continuous Current ³	I_S		$I_F = 9A, V_{GS} = 0V$	Q1			9	A	
				Q2			9		
Forward Voltage ¹	V_{SD}			Q1			1.3	V	
		Q2		0.7					
Reverse Recovery Time	t_{rr}	$I_F = 9A, di_F/dt = 100A / \mu S$		Q1	13	nS			
				Q2	14				
Reverse Recovery Charge	Q_{rr}		Q1	3.2	nC				
			Q2	3					

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

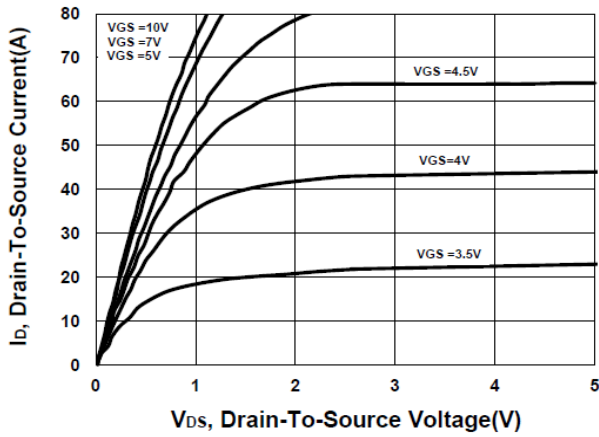
²Independent of operating temperature.

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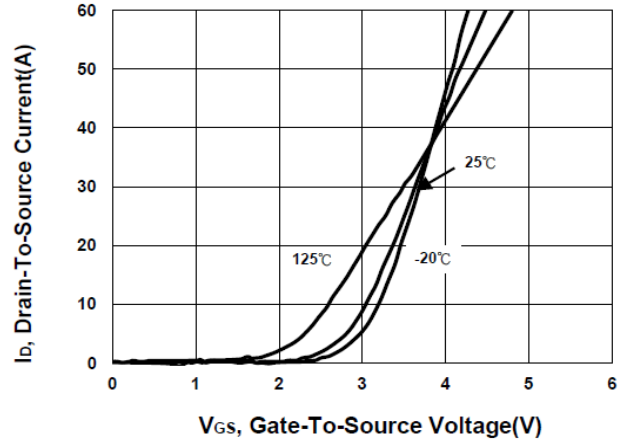
Dual N-Channel Enhancement Mode MOSFET

Q1

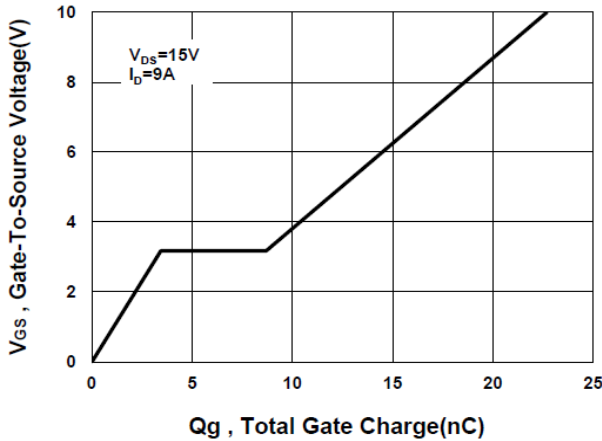
Output Characteristics



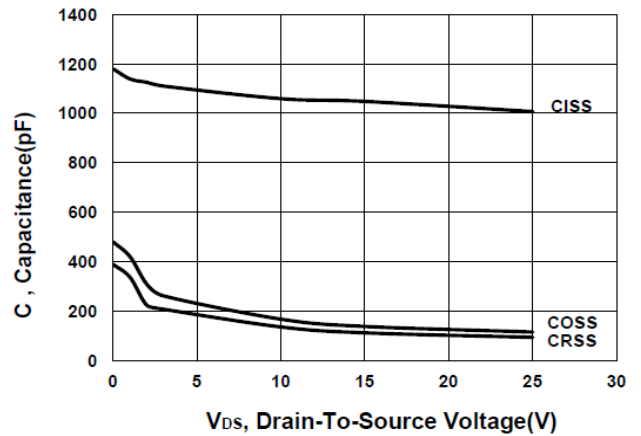
Transfer Characteristics



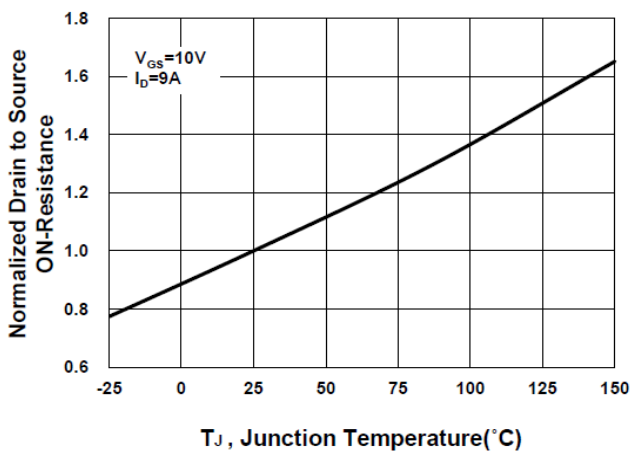
Gate charge Characteristics



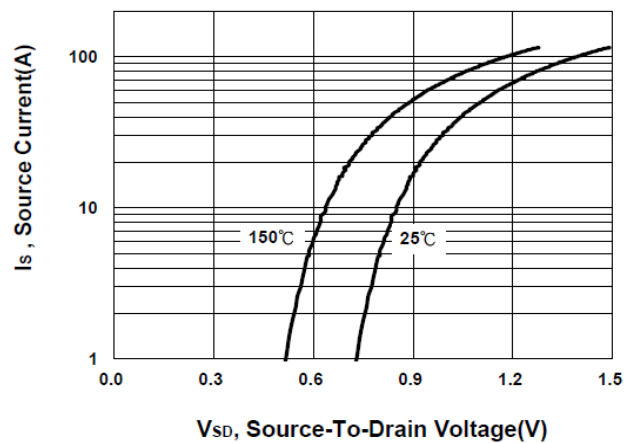
Capacitance Characteristic



On-Resistance VS Temperature



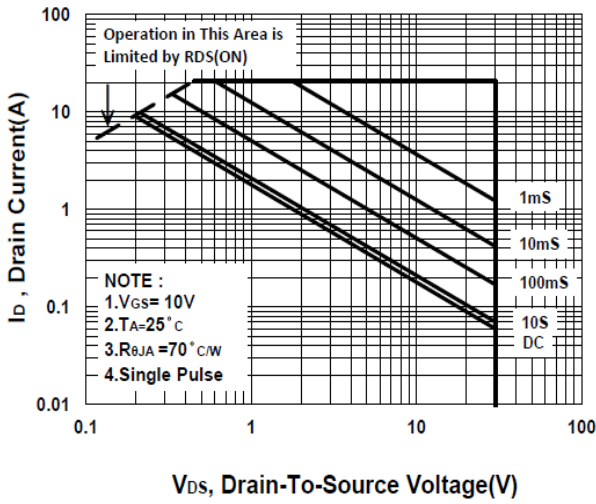
Source-Drain Diode Forward Voltage



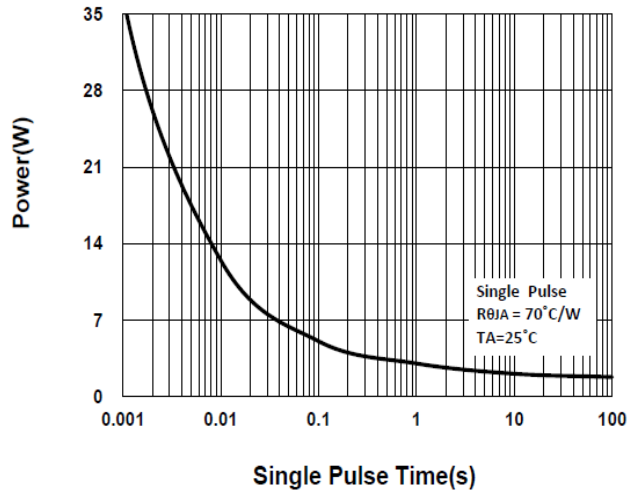
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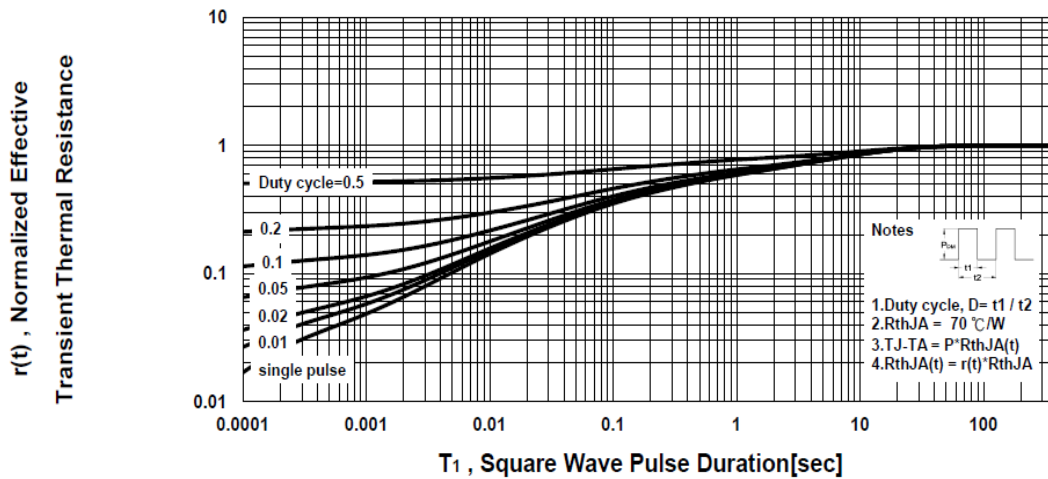
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

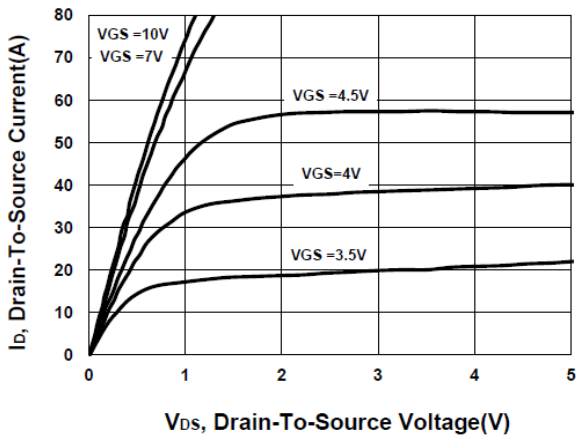


PD1303YVS

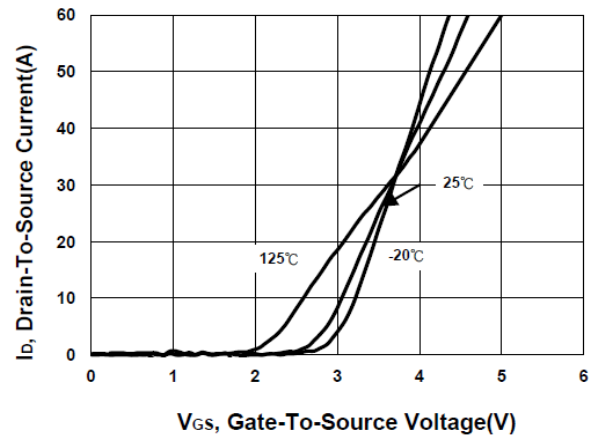
Dual N-Channel Enhancement Mode MOSFET

Q2

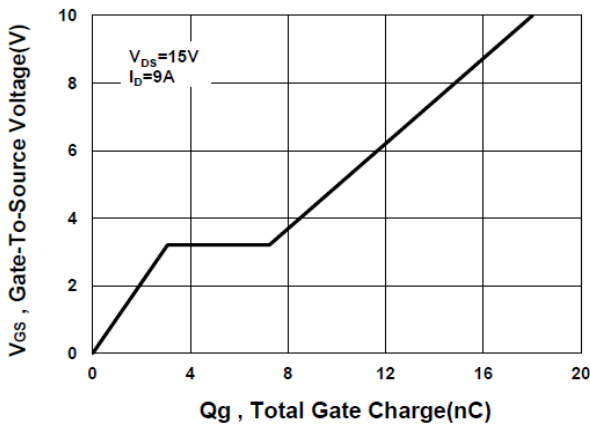
Output Characteristics



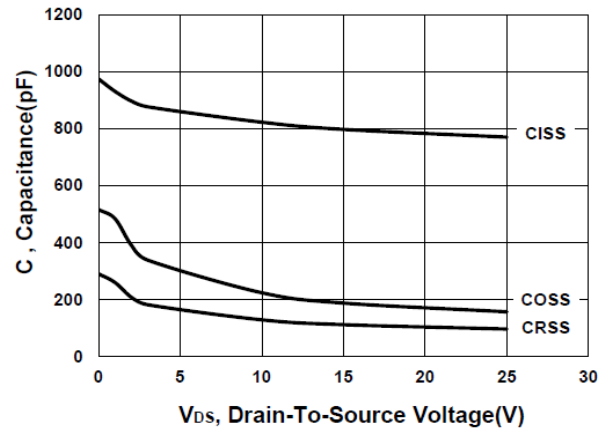
Transfer Characteristics



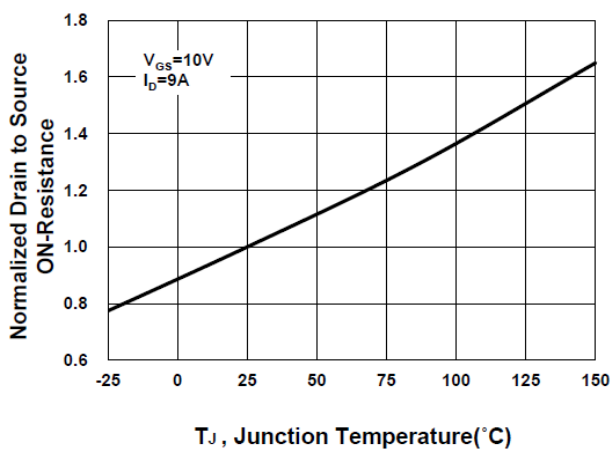
Gate charge Characteristics



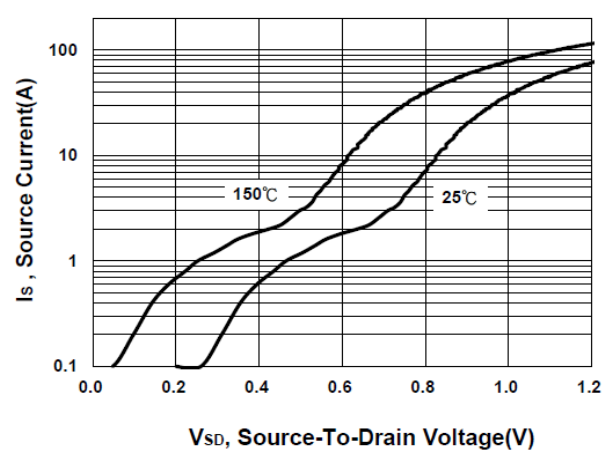
Capacitance Characteristic



On-Resistance VS Temperature



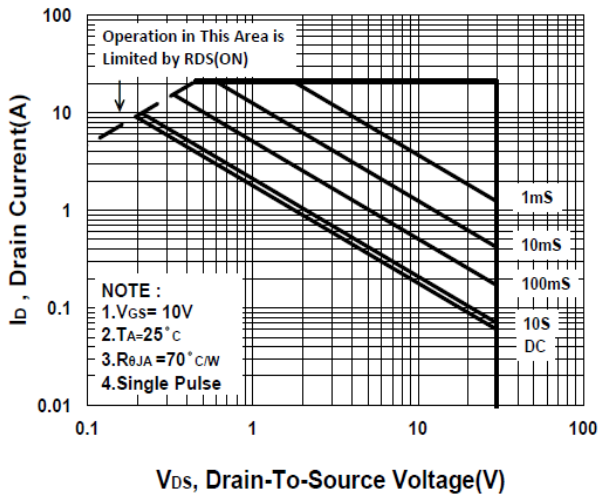
Source-Drain Diode Forward Voltage



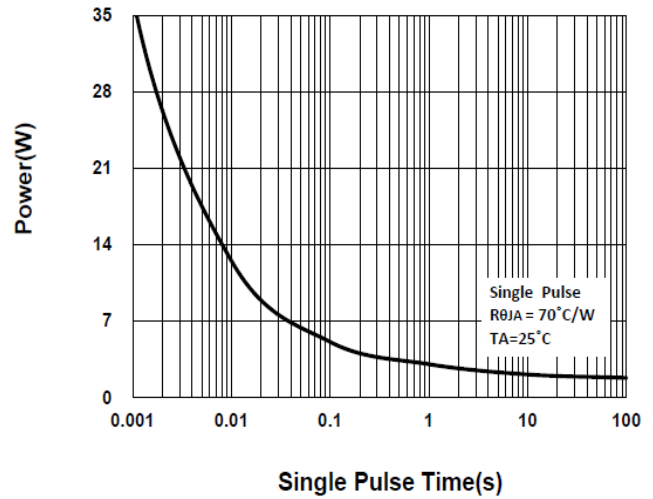
PD1303YVS

Dual N-Channel Enhancement Mode MOSFET

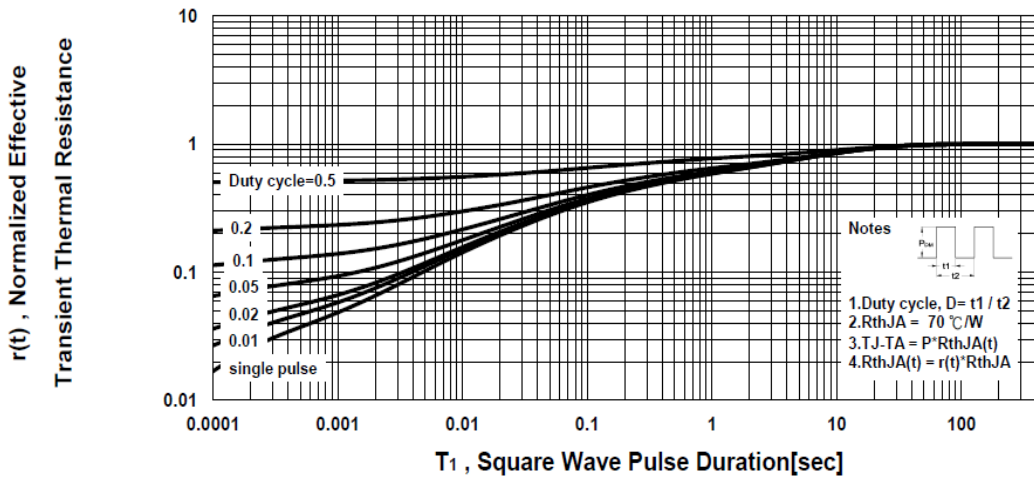
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



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Package Dimension

SOP-8 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25				

